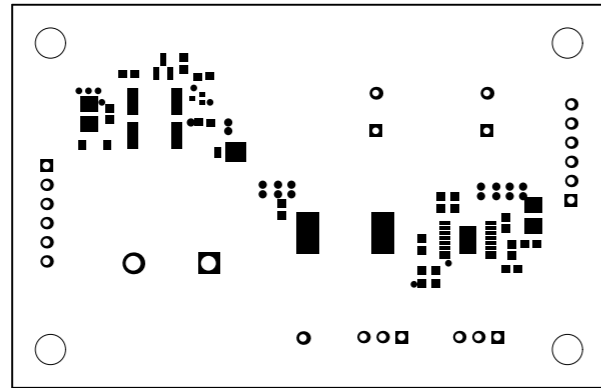
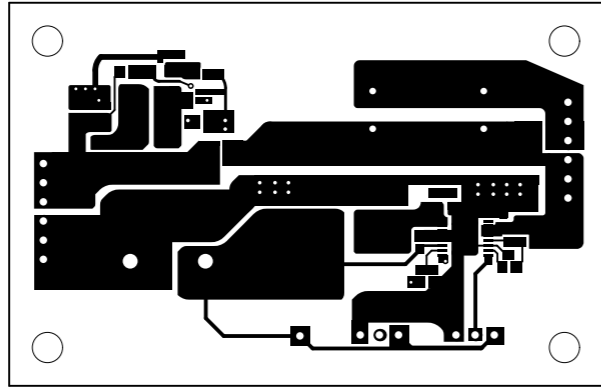


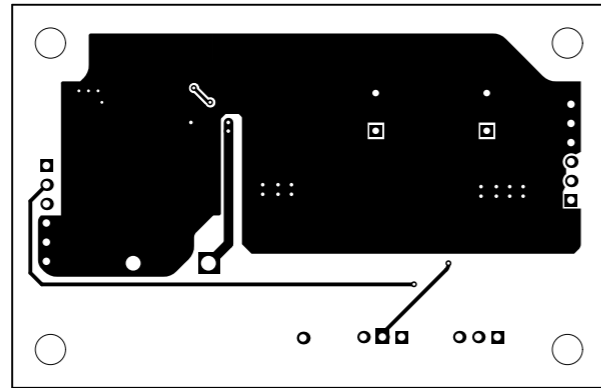
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9755	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 2014/10/18 22:04:34	TEXAS INSTRUMENTS	



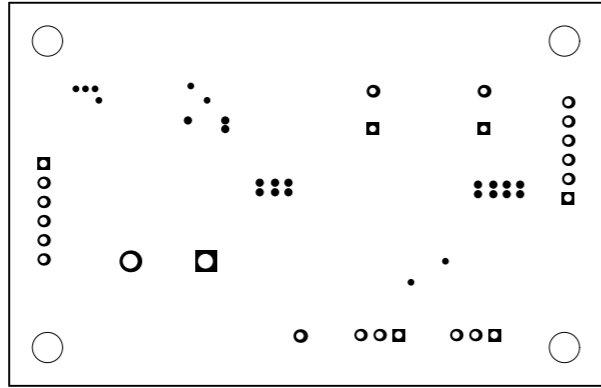
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9755	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 2014/10/18 22:04:35	TEXAS INSTRUMENTS	



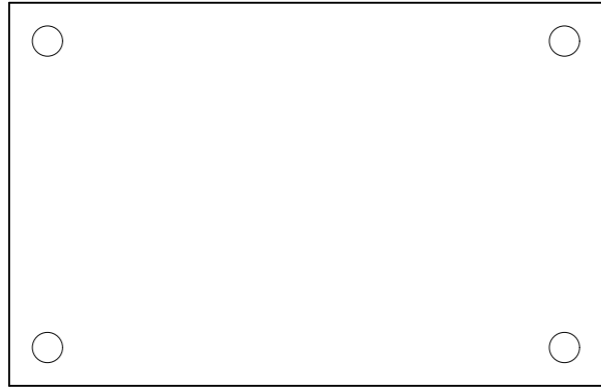
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9755	REV: A	SUN REV: Not In VersionControl
LAYER NAME = L1 Top Layer			
PLOT NAME = Top Layer	GENERATED : 2014/10/18 22:04:36	TEXAS INSTRUMENTS	



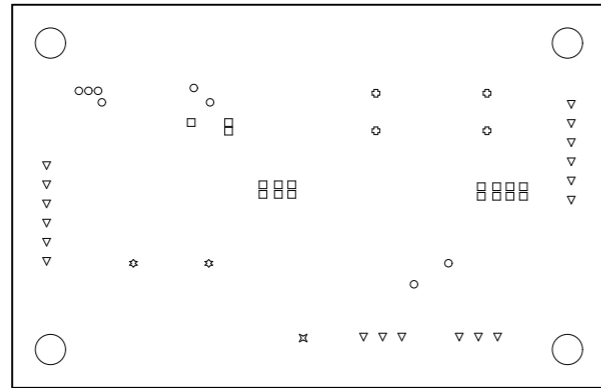
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9755	REV: A	SUN REV: Not In VersionControl
LAYER NAME = L2 Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 2014/10/18 22:04:36	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9755	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 2014/10/18 22:04:37	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9755	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 2014/10/18 22:04:37	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	8	16mil (0.406mm)	PTH	Round
□	17	20mil (0.508mm)	PTH	Round
⊙	4	35.433mil (0.9mm)	PTH	Round
▽	18	40mil (1.016mm)	PTH	Round
⊠	1	40.157mil (1.02mm)	PTH	Round
☆	2	78.74mil (2mm)	PTH	Round
50 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9755	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 2014/10/18 22:04:38	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9755	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Board Dimensions	GENERATED : 2014/10/18 22:04:38	TEXAS INSTRUMENTS	

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